



Customer Information Notification

202105012I : NXP ATTJ Final Test Site Relocation from ATTJ to ATTJ Building 2 (ATTJ-B2)

Note: This notice is NXP Company Proprietary.

Issue Date: May 12, 2021 **Effective date:** Jun 07, 2021

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Management summary

NXP ATTJ Final Test Site Relocation from ATTJ to ATTJ Building 2 (ATTJ-B2).

Change Category

- Wafer Fab Process
- Assembly Process
- Product Marking
- Test Process
- Design
- Wafer Fab Materials
- Assembly Materials
- Mechanical Specification
- Test Equipment
- Errata
- Wafer Fab Location
- Assembly Location
- Packing/Shipping/Labeling
- Test Location
- Electrical spec./Test coverage
- Firmware
- Other

PCN Overview

Description

NXP is pleased to announce the relocation of the Final Test Site from the current NXP ATTJ, Tianjin, China test site to the NXP ATTJ Building 2 (ATTJ-B2) located 2.5km away from the current site to create a consolidated ATTJ Test Center of Excellence. Correspondingly, the Test Backend Shipping / Packing Operations will relocate to the ATTJ-B2 site as well.

All current ATTJ Final Test equipment (hardware / software), test flows, test programs, policies, procedures, and personnel will relocate to the new ATTJ-B2 site with no impact to product form, fit, function or reliability.

Reason

This major, strategic NXP initiative ensures future scalability of NXP ATTJ backend manufacturing sites, ATTJ main factory and new ATTJ-B2, to support current and future business. The current ATTJ main factory manufacturing floor space is fully utilized. Final Test and Test Backend Shipping / Packing Operations must be migrated to the new ATTJ-B2 Test Center of Excellence, while the existing ATTJ main factory will be exclusive for assembly and other non-Final Test operations. This

initiative allows growth opportunities for both ATTJ manufacturing buildings for customer supply assurance.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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